HOSTAFORM® C 27021 XAP®2

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Polyacetalcopolymer Easy flow injection molding grade with reduced emissions especially for automotive interior application. Burning rate according to FMVSS 302 < 100 mm/min (1 mm thickness) Emission according to VDA 275 < 2 mg/kg (natural grades) Emission according to VDA 275 < 5 mg/kg (colored grades).

Product information

Resin Identification	POM		ISO 1043
Part Marking Code	>POM<		ISO 11469

Rheological properties

Melt volume-flow rate	24	cm^3/10min	ISO 1133
Temperature	374	°F	
Load	4.76	lb	

Typical mechanical properties

Tensile modulus	399000	psi	ISO 527-1/-2
Tensile stress at yield, 50mm/min	9300	psi	ISO 527-1/-2
Tensile strain at yield, 50mm/min	7.5	%	ISO 527-1/-2
Nominal strain at break	17	%	ISO 527-1/-2
Flexural modulus	377000	psi	ISO 178
Tensile creep modulus, 1h	348000	psi	ISO 899-1
Tensile creep modulus, 1000h	174000	psi	ISO 899-1
Charpy impact strength, 23°C	80.9	$ftlb/in^2$	ISO 179/1eU
Charpy impact strength, -30°C	80.9	$ftlb/in^2$	ISO 179/1eU
Charpy notched impact strength, 23°C	2.62	$ftlb/in^2$	ISO 179/1eA
Charpy notched impact strength, -30°C	2.62	$ftlb/in^2$	ISO 179/1eA

Thermal properties

Melting temperature, 10°C/min	327	°F	ISO 11357-1/-3
Coefficient of linear thermal expansion (CLTE), parallel	0.67	E-4/°F	ISO 11359-1/-2
Coefficient of linear thermal expansion (CLTE), normal	0.667	E-4/°F	ISO 11359-1/-2

Electrical properties

Relative permittivity, 100Hz	4		IEC 62631-2-1
Relative permittivity, 1MHz	4		IEC 62631-2-1
Dissipation factor, 100Hz	20	E-4	IEC 62631-2-1
Dissipation factor, 1MHz	50	E-4	IEC 62631-2-1
Volume resistivity	1E12	Ohm.m	IEC 62631-3-1
Surface resistivity	1E14	Ohm	IEC 62631-3-2
Electric strength	889	kV/in	IEC 60243-1
Comparative tracking index	600		IEC 60112

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Physical/Other properties

Humidity absorption, 2mm	0.2	%	Sim. to ISO 62
Water absorption, 2mm	0.65	%	Sim. to ISO 62
Density	0.0509	lb/in³	ISO 1183

Injection

Drying Recommended	no	
Drying Temperature	212	°F
Drying Time, Dehumidified Dryer	3 - 4	h
Processing Moisture Content	≤0.2	%
Melt Temperature Optimum	374	°F
Min. melt temperature	356	°F
Max. melt temperature	392	°F
Max. screw tangential speed	≤0.3	m/s
Mold Temperature Optimum	212	°F
Min. mold temperature	176	°F
Max. mold temperature	248	°F
Hold pressure range	8700 - 17400	psi
Hold Pressure Time (h is the max. wall thickness of the part in mm)	2h²-3	s
Back pressure	580	psi

Automotive

OEM	STANDARD	ADDITIONAL INFORMATION
Ford	WSK-M4D635-A3	
Li Auto	Q/LiA5310020	2021 (V2)
Mercedes-Benz	DBL5404	BQF
Mercedes-Benz	DBL5410	
Renault	EP10-1c, No Spec, Special Part Approval, See Your CE Account Manager.	
VW Group	TL 524 76	

Characteristics

Processing	Injection Molding
Special characteristics	Low emissions

Additional information

Injection molding

Preprocessing

To achive low emission values pre drying using a recirculating air dryer (100 to 120 °C / max. 40 mm layer / 3 to 6 hours) is recommended.

Max. Water content 0,1 %

Processing

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Standard injection moulding machines with three phase (15 to 25 D) plasticating screws will fit.

Postprocessing

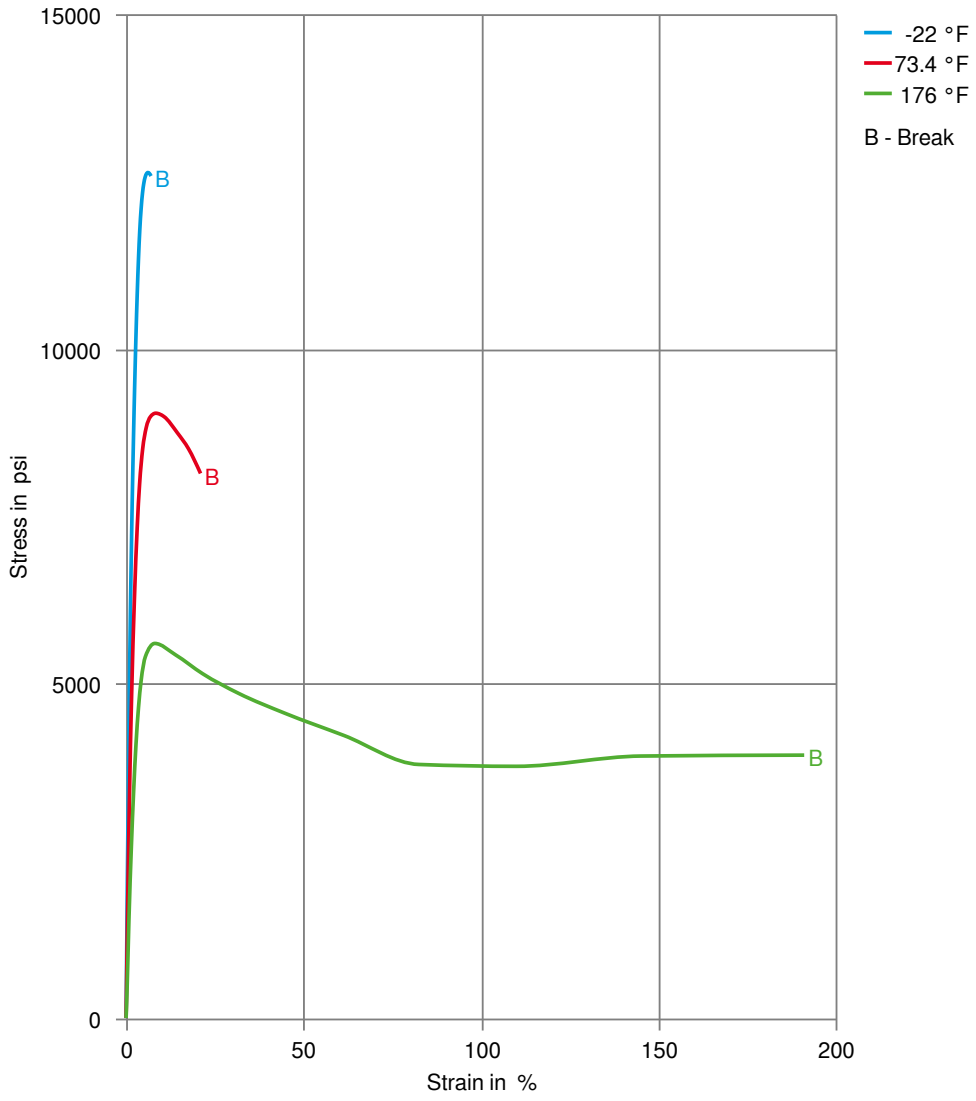
Conditioning e.g. moisturizing is not necessary.

Processing Notes

Pre-Drying

recommended

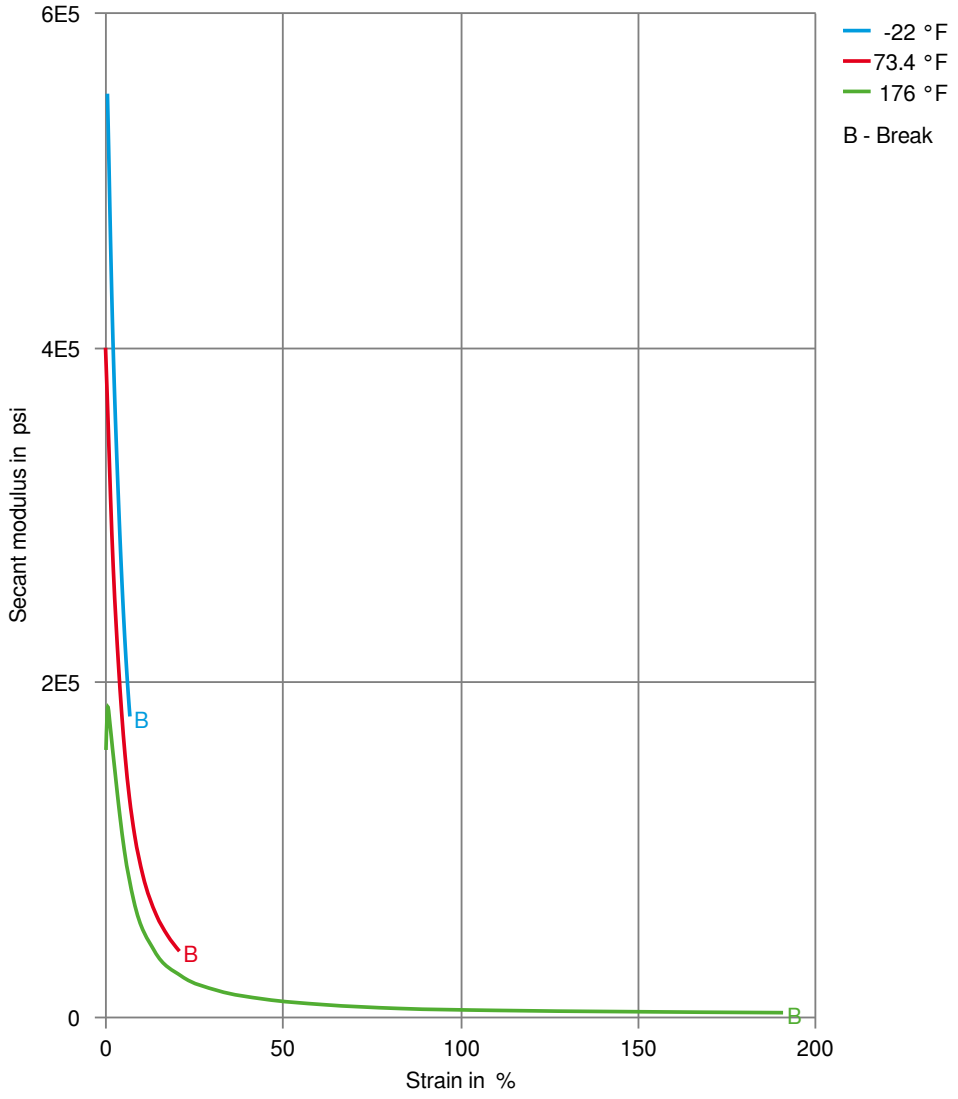
Stress-strain



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Secant modulus-strain



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